

Title (en)
COPPER ALLOY MATERIAL FOR ELECTRIC AND ELECTRONIC APPARATUSES, AND ELECTRIC AND ELECTRONIC COMPONENTS

Title (de)
KUPFERLEGIERUNGSMATERIAL FÜR ELEKTRISCHE UND ELEKTRONISCHE VORRICHTUNGEN SOWIE ELEKTRISCHE UND ELEKTRONISCHE BAUTEILE

Title (fr)
MATÉRIAU D'ALLIAGE DE CUIVRE DESTINÉ À DES APPAREILS ÉLECTRIQUES ET ÉLECTRONIQUES, ET COMPOSANTS ÉLECTRIQUES ET ÉLECTRONIQUES

Publication
EP 2270242 A4 20120627 (EN)

Application
EP 09728058 A 20090330

Priority
• JP 2009056576 W 20090330
• JP 2008092315 A 20080331

Abstract (en)
[origin: EP2270242A1] A copper alloy material for an electrical/electronic equipment, containing Ni 3.3 to 5.0 mass%, having a content of Si within the range of 2.8 to 3.8 in terms of a mass ratio of Ni and Si (Ni/Si), and containing Mg 0.01 to 0.2 mass%, Sn 0.05 to 1.5 mass%, and Zn 0.2 to 1.5 mass%, with the balance of Cu and inevitable impurities, wherein when a test piece with thickness t of 0.20 mm and width w of 2.0 mm is subjected to 90° W-bending with bending radius R of 0.1 mm, no cracks occur on the test piece; and, an electrical/electronic part obtained by working the same.

IPC 8 full level
C22C 9/06 (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01); **H01B 1/02** (2006.01); **H01B 13/00** (2006.01); **H01L 23/48** (2006.01)

CPC (source: EP US)
C22C 9/06 (2013.01 - EP US); **C22F 1/08** (2013.01 - EP US); **H01B 1/026** (2013.01 - EP US)

Citation (search report)
• [E] EP 2143810 A1 20100113 - FURUKAWA ELECTRIC CO LTD [JP]
• [I] US 2005263218 A1 20051201 - TANAKA NOBUYUKI [JP], et al
• [A] US 2002119071 A1 20020829 - USAMI TAKAYUKI [JP], et al
• See references of WO 2009123159A1

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)
EP 2270242 A1 20110105; **EP 2270242 A4 20120627**; **EP 2270242 B1 20140604**; CN 101981213 A 20110223; CN 101981213 B 20121114; JP 4653240 B2 20110316; JP WO2009123159 A1 20110728; KR 101114116 B1 20120313; KR 20100132044 A 20101216; US 2011017357 A1 20110127; WO 2009123159 A1 20091008

DOCDB simple family (application)
EP 09728058 A 20090330; CN 200980111781 A 20090330; JP 2009056576 W 20090330; JP 2009536501 A 20090330; KR 20107023904 A 20090330; US 89389310 A 20100929